

CLAIMS

What is claimed is:

1 1. A method for adhesively bonding two surfaces
2 together which comprises providing on one of said surfaces a
3 central single point adhesive contact deposit;

4 providing on one of said surfaces adhesive extending
5 outward from a central portion deposit in a spoke-like array
6 diagonally across substantially the entire surface;

7 bringing together said two surfaces, one on top of the
8 other, with the adhesive located between said surfaces to
9 cause said adhesive to spread out and cover said surfaces to
10 thereby bond them together.

11 2. The method of claim 1 wherein said central, single
12 point adhesive contact deposit is a dot-like generally
13 hemispherically shaped adhesive deposit.

14 3. The method of claim 1 wherein said adhesive has a
15 viscosity of greater than 30,000 centipoise.

16 4. The method of claim 1 wherein said adhesive has a
17 viscosity of less than 30,000 centipoise and the central
18 single point adhesive contact deposit is located on the
19 surface that is located as the upper surface during the
20 bonding; and said central portion deposit has a diameter at
21 least as large as the diameter of said single paint adhesive
22 contact deposit for contacting with said single point
23 adhesive contact deposit during bonding.

24 5. The method of claim 1 wherein said surfaces are
25 flat.

1 6. The method of claim 5 wherein said flat surfaces
2 are glass.

1 7. The method of claim 5 wherein said flat surfaces
2 are glass panels for fabricating large liquid crystal
3 display assemblies.

1 8. The method of claim 1 wherein one of the surfaces
2 has a smaller area than the other of the surfaces.

1 9. The method of claim 1 wherein the adhesive is a
2 thermosetting adhesive.

1 10. The method of claim 1 wherein said spoke-like
2 array comprises at least four spoke-like adhesive deposits.

1 11. The method of claim 1 wherein said spoke-like
2 array comprises up to eight spoke-like adhesive deposits.

1 12. The method of claim 1 wherein each of said spoke-
2 like deposits is about 2 to about 50 mils thick.

1 13. The method of claim 2 wherein said deposit has a
2 diameter of about 30 mils to about 1/4" and a height of
3 about 15 mils to about 1/8".

1 14. The method of claim 13 wherein said dot-like
2 generally hemispherical shaped adhesive deposit has a
3 diameter of about 60 to about 100 mils and a height of about
4 30 to about 50 mils.

1 15. The method of claim 13 wherein the height of the
2 spoke-like deposits is about 2 to about 50 mils.

1 16. An assembly for bonding two surfaces together
2 which comprises a central, single point adhesive contact
3 located on one of said surfaces; and adhesive extending from
4 a central point deposit in a spoke-like array diagonally
5 across substantially the entire surface of one of said
6 surfaces.

1 17. The assembly of claim 16 wherein said spoke-like
2 array comprises at least four spoke-like adhesive deposits.

1 18. The assembly of claim 16 wherein said spoke-like
2 array comprises up to eight spoke-like adhesive deposits.

1 19. The assembly of claim 16 wherein each of said
2 spoke-like deposits are about 2 to about 50 mils thick.

1 20. The assembly of claim 16 wherein said central,
2 single point adhesive contact deposit is a dot-like
3 generally hemispherical shaped adhesive deposit.

1 21. The assembly of claim 20 wherein said deposit has
2 a diameter of about 30 mils to about 1/4" and a height of
3 about 15 mils to about 1/8".

1 22. The assembly of claim 21 wherein said dot-like
2 generally hemispherical shaped adhesive deposit has a
3 diameter of about 60 to about 100 mils and a height of about
4 30 to about 50 mils.

1 23. The assembly of claim 21 wherein the height of the
2 spoke-like deposits is about 2 to about 50 mils.

1 24. The assembly of claim 16 wherein said adhesive has
2 a viscosity of less than 30,000 centipoise.

1 25. The assembly of claim 16 wherein said adhesive is
2 a thermosetting adhesive.

1 26. The assembly of claim 16 wherein said surfaces are
2 flat.

1 27. The assembly of claim 16 wherein said central
2 single point adhesive contact is located on one of the
3 surfaces and the spoke-like array on the other surface.

1 28. An article comprising two surfaces bonded together
2 wherein one of said surfaces has a smaller surface area than
3 that of the other of said surfaces; said surfaces are bonded
4 together by an adhesive located between said surfaces over
5 the entire area of the smaller area surface; said adhesive
6 being void-free and exhibiting a wavelike undulating profile
7 at the edges of the smaller surface.

1 29. The article of claim 28 wherein said adhesive is a
2 thermosetting adhesive.

1 30. The article of claim 28 wherein said surfaces are
2 flat.

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